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ABSTRACT

5 A die frame is disclosed, including: an upper die holder, an upper pressure plate and a lower die holder. The upper pressure plate is connected below the upper die holder, and a lower end face of the upper pressure plate is configured to mount an etching die. The lower die holder is correspondingly arranged below the upper die holder and configured to bear materials. The lower end face of the upper pressure plate or an upper end face of the lower die holder is provided with a boss thicker than the etching die, so that an uncut height is reserved between the etching die and the lower die holder during die closing, and the uncut height is equal to a thickness difference between the boss and the etching die. With the die frame, materials will not be over-cut, and the service life of the etching die can be
10 prolonged.

(To be published with FIG. 1)